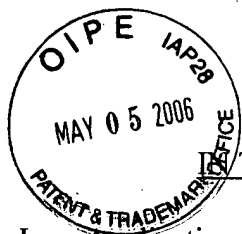


ITW



Attorney Docket no: 0553-0193.01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Takayama et al.

Serial No.: 10/672,521

Filed: September 26, 2003

For: Wiring Material, Semiconductor Device
Provided With A Wiring Using The Wiring
Material And Method of Manufacturing
Thereof

Examiner: Ha T. Nguyen

Art Unit: 2812

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:
Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450 on

May 3, 2006
(Date of Deposit)

Shannon Wallace

Name of applicant, assignee, or Registered Rep.
Shannon Wallace 5/3/06
Signature Date

AMENDMENT E

In response to the Office Action of February 3, 2006, please amend the above-identified application as follows: